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(57) **ABSTRACT**

A circuit module includes an interposer, and the interposer includes an element body including a first surface, a first interposer terminal provided on the first surface of the element body, and connected to a first external element, a second interposer terminal provided on the first surface of the element body, and connected to a second external element, a first wiring provided in the element body, and electrically connecting the first interposer terminal and the circuit board with each other, a second wiring provided in the element body, and electrically connecting the second interposer terminal and the circuit board with each other, and a bypass wiring provided in the element body and/or on a surface of the element body, and electrically connecting the first interposer terminal and the second interposer terminal with each other.

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